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(12) **United States Design Patent**
Kaneko et al.

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(54) **OUTER TUBE FOR PROCESS TUBE FOR MANUFACTURING SEMICONDUCTOR WAFERS**

(75) Inventors: **Hirofumi Kaneko**, Oshu (JP); **Atsushi Endo**, Nirasaki (JP)

(73) Assignee: **Tokyo Electron Limited**, Minato-Ku (JP)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
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See application file for complete search history.

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Primary Examiner — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Burr & Brown, PLLC

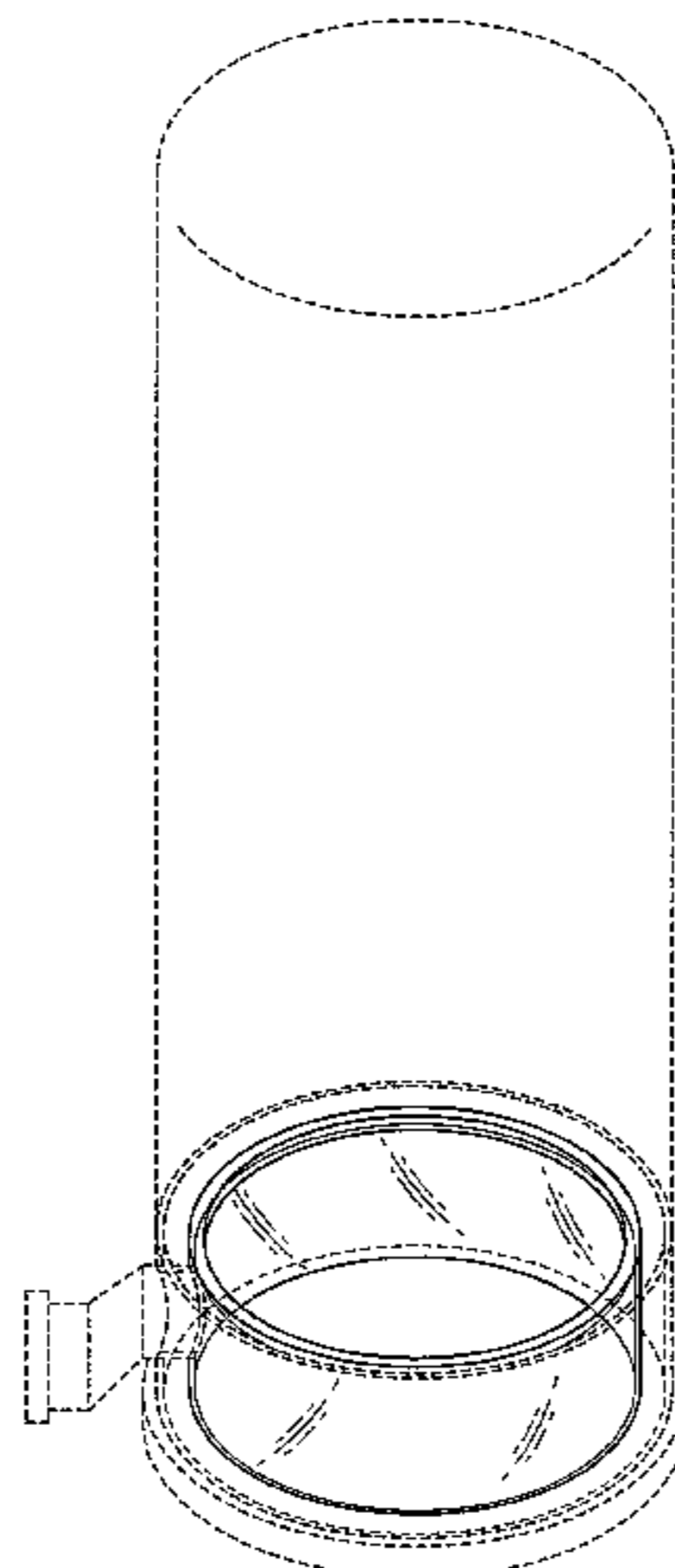
(57) **CLAIM**

The ornamental design for an outer tube for process tube for manufacturing semiconductor wafers, as shown and described.

DESCRIPTION

FIG. 1 is perspective view of an outer tube for process tube for manufacturing semiconductor wafers showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a right side thereof;
FIG. 5 is a left side view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof; and,
FIG. 8 is a cross-sectional view taken along line 8-8 of FIG. 6.
The broken lines shown in the drawings represent portions of the outer tube for process tube for manufacturing semiconductor wafers that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



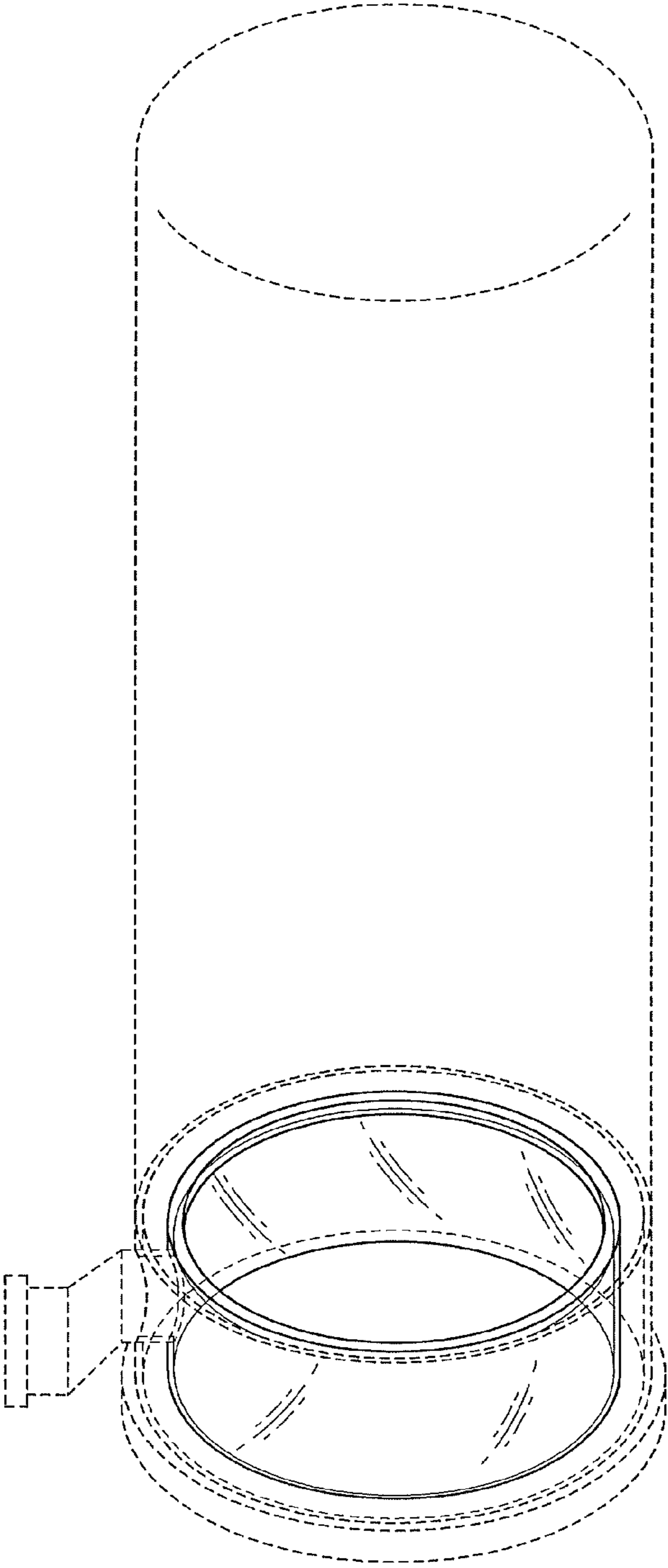


FIG. 1

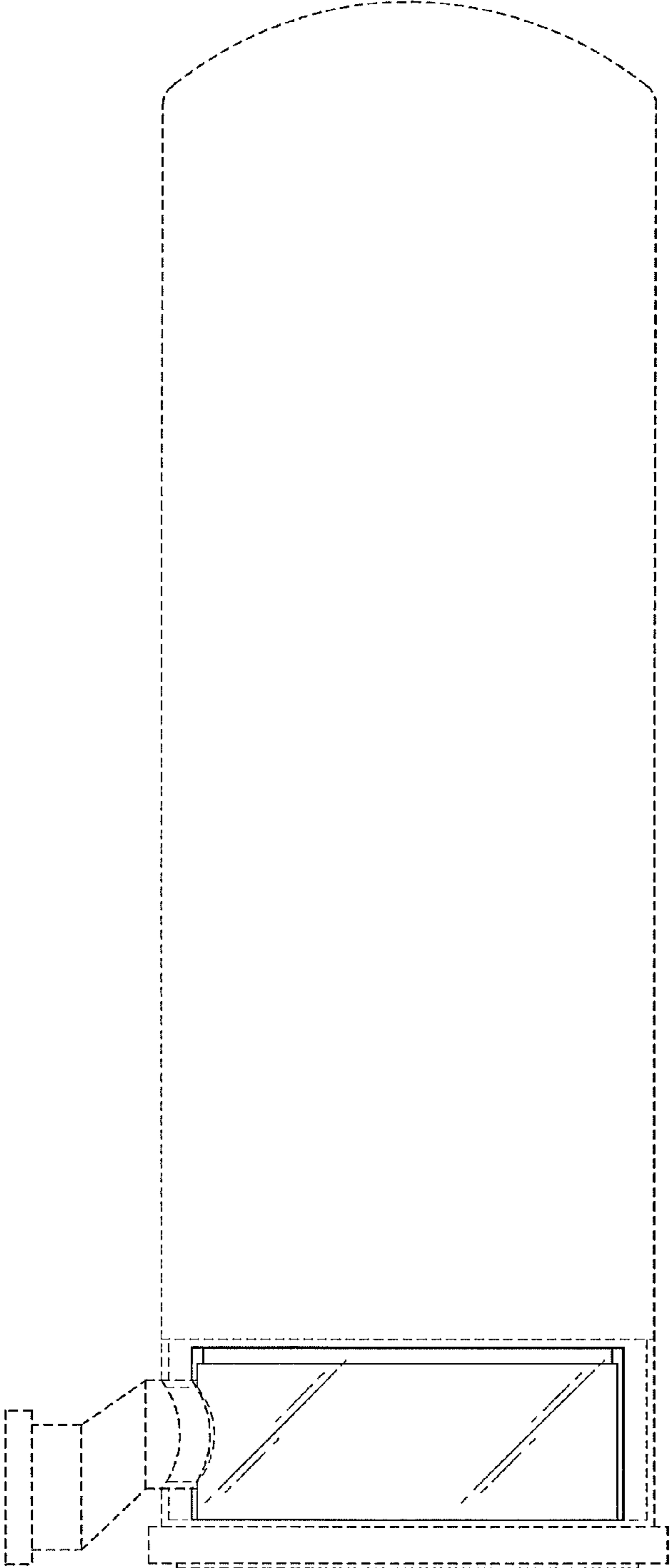


FIG. 2

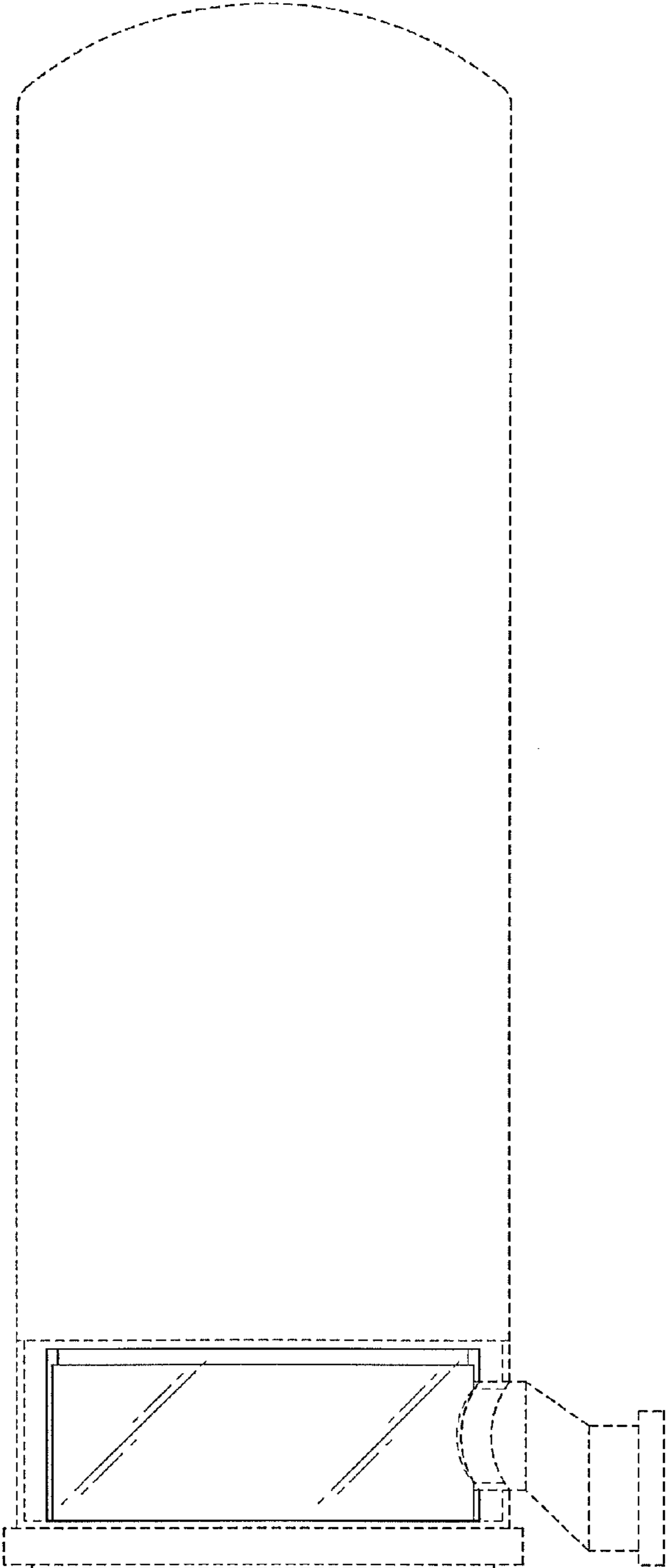


FIG. 3

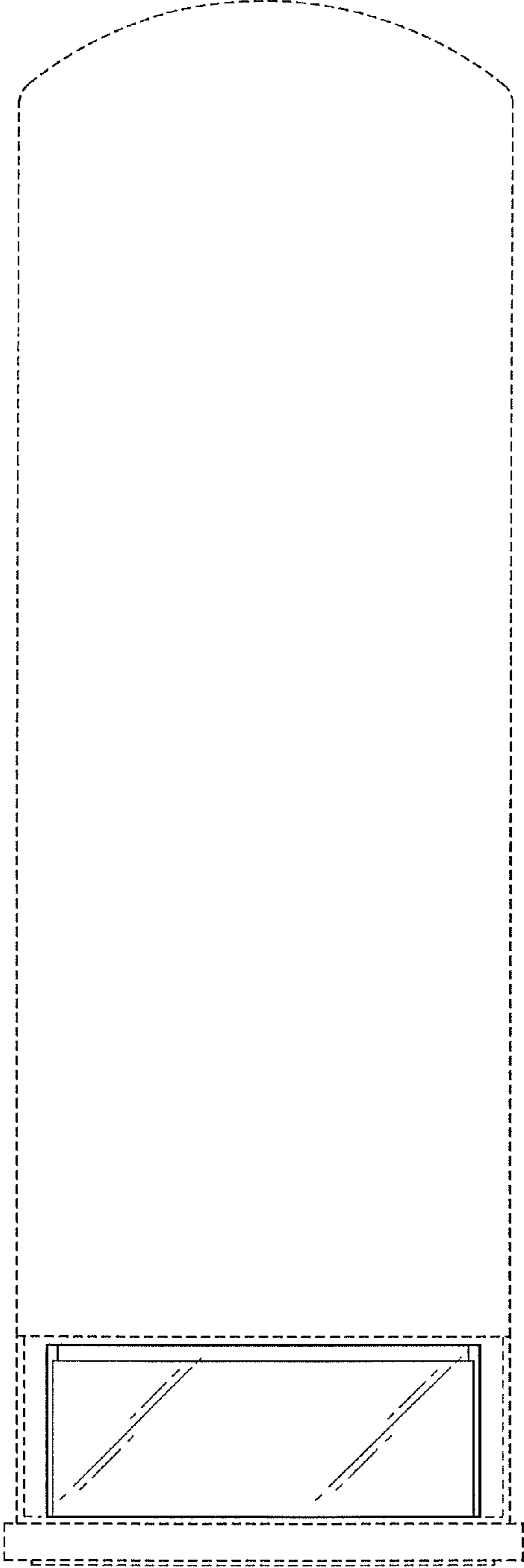


FIG. 4

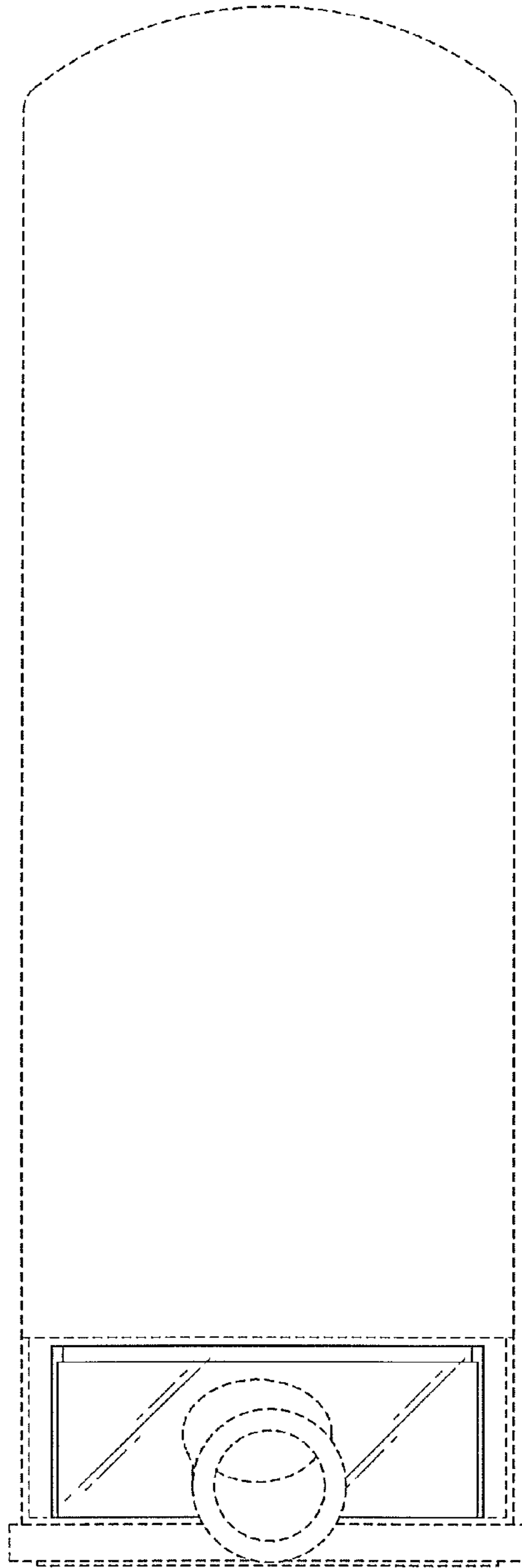


FIG. 5

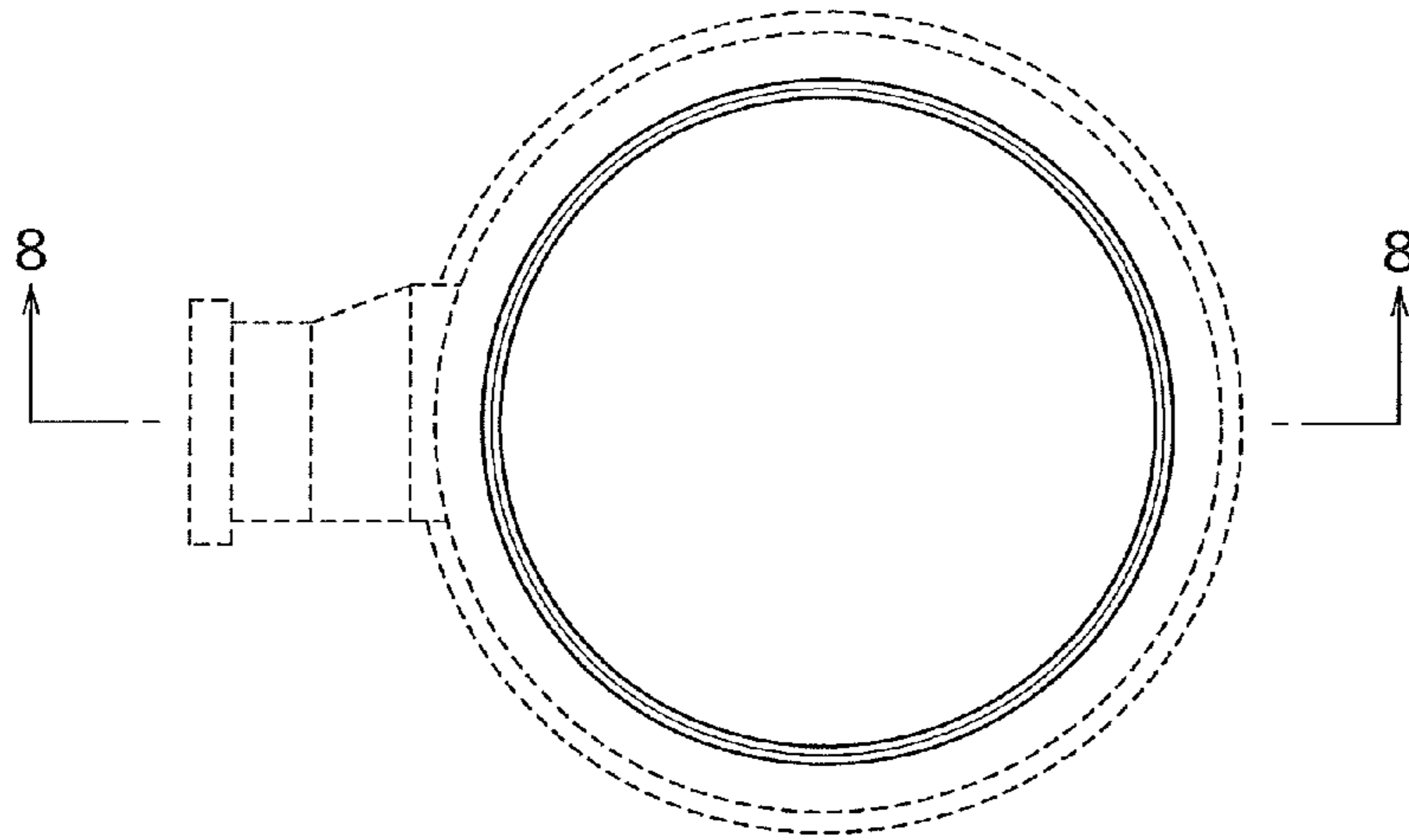


FIG. 6

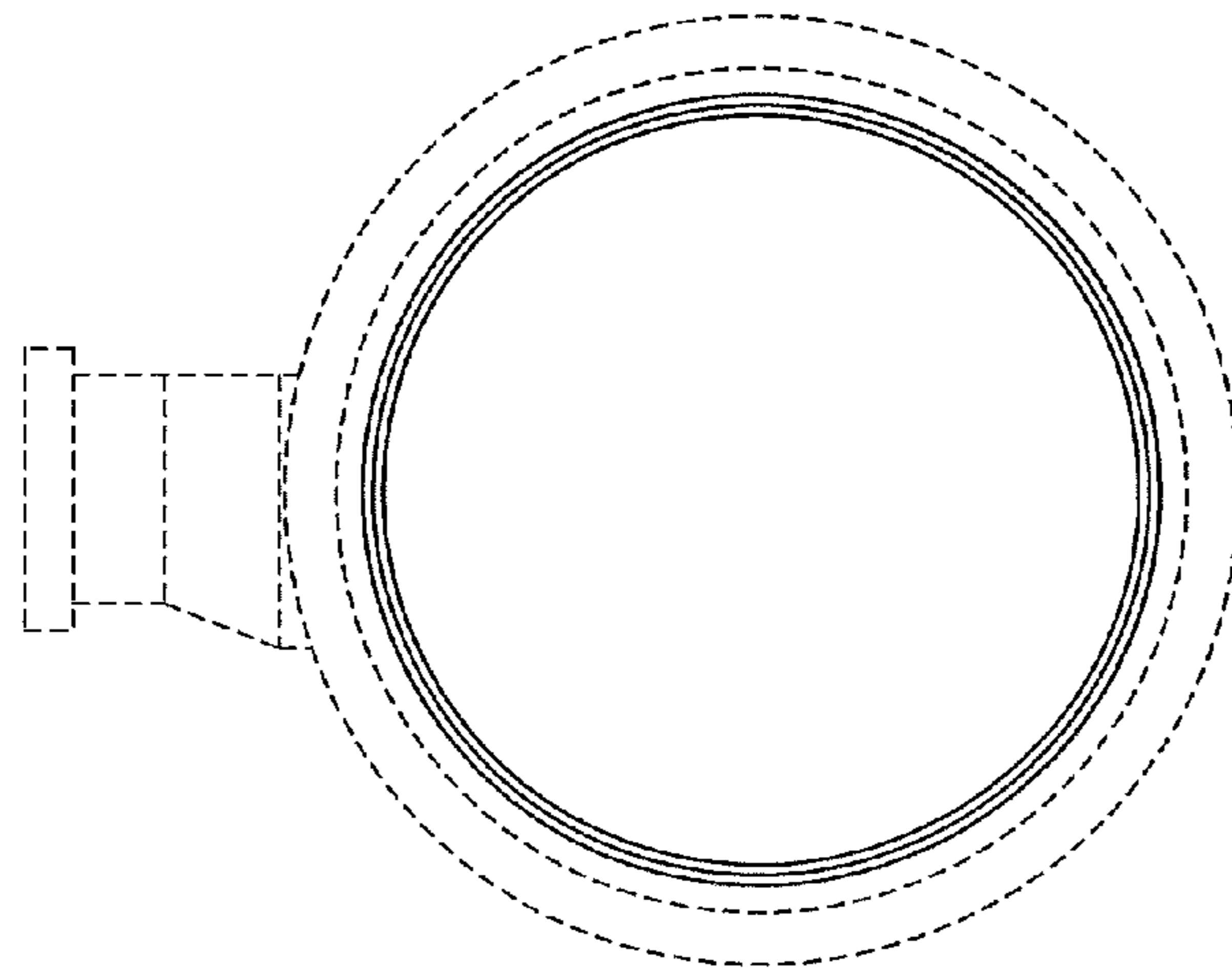


FIG. 7

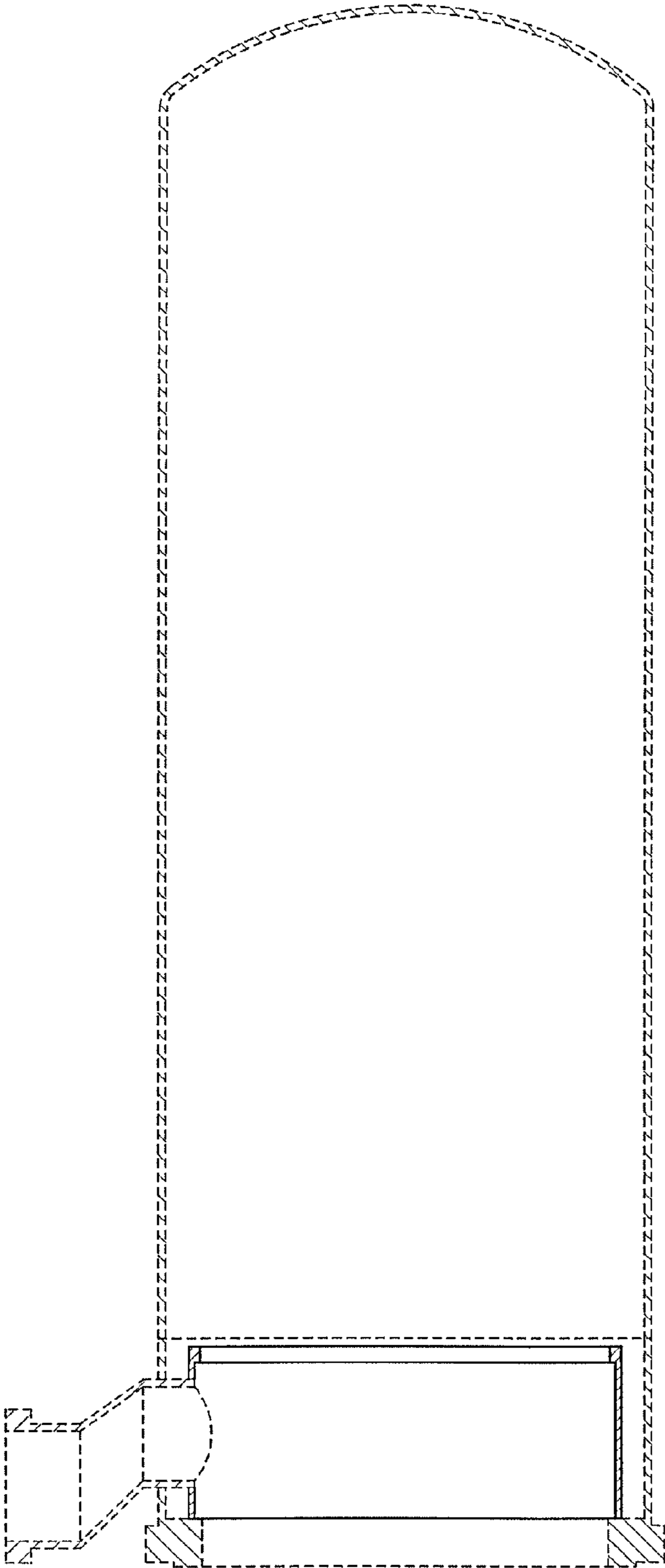


FIG. 8